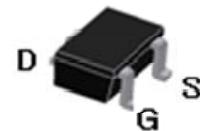
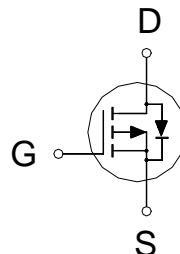


P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	-20V
R _{DSON} (MAX.)	100mΩ
I _D	-3.4A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	-3.4	A
		-2.4	
Pulsed Drain Current ¹	I _{DM}	-14	
Power Dissipation	P _D	1.04	W
		0.66	
Operating Junction & Storage Temperature Range	T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient ³	R _{θJA} (T ≤ 10sec)		83	°C / W
	R _{θJA} (Steady State)		120	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³The device mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

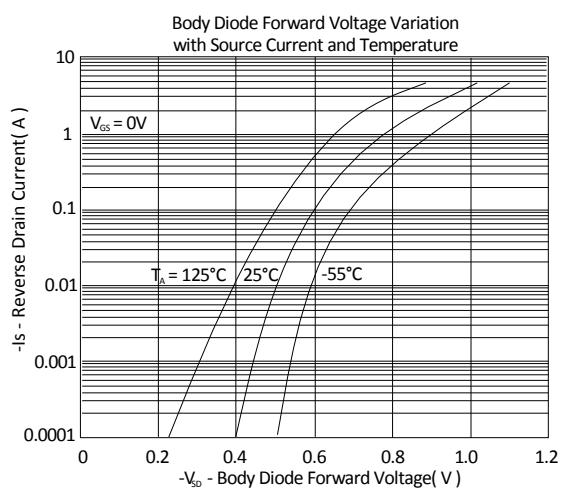
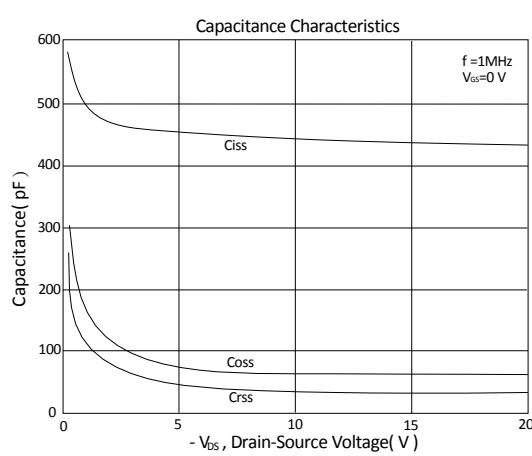
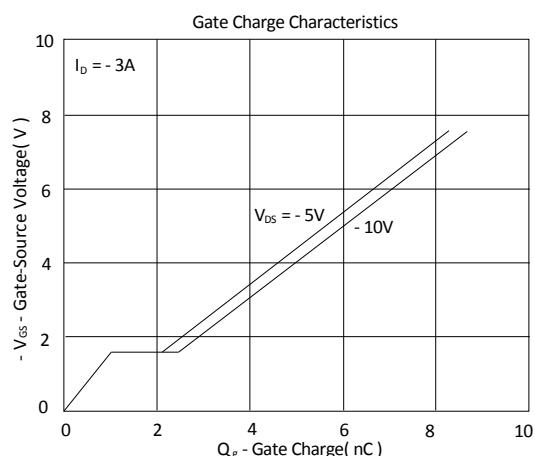
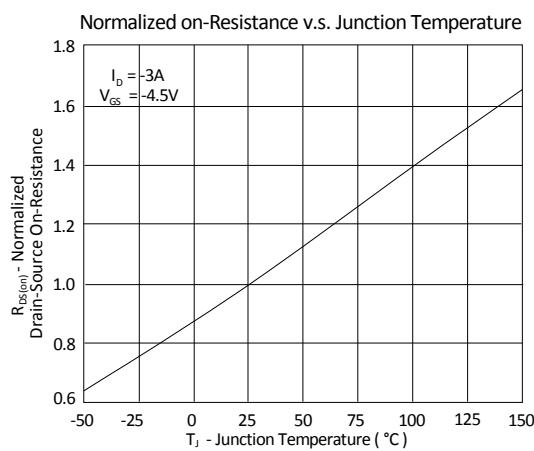
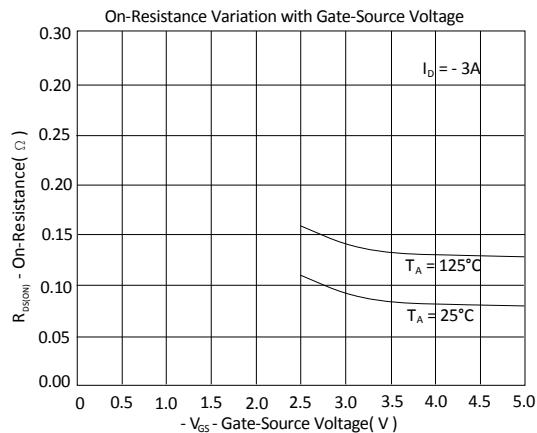
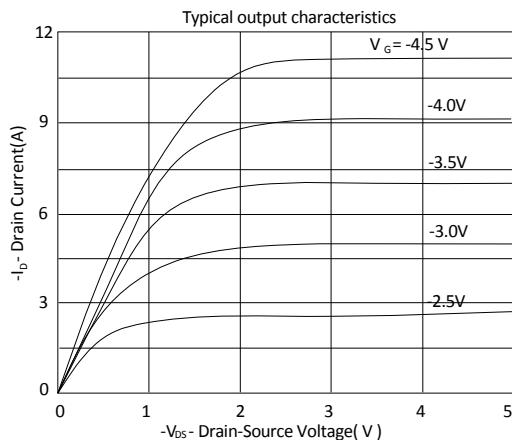
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.3	-0.75	-1.2	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 12\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -16\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
		$V_{\text{DS}} = -16\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -4.5\text{V}$	-3.4			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -3.4\text{A}$		83	100	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{V}, I_D = -2.5\text{A}$		110	135	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_D = -3\text{A}$		4.5		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -10\text{V}, f = 1\text{MHz}$		450		
Output Capacitance	C_{oss}			58		pF
Reverse Transfer Capacitance	C_{rss}			41		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		5.4		
Gate-Source Charge ^{1,2}	Q_{gs}			1.0		nC
Gate-Drain Charge ^{1,2}	Q_{gd}			1.3		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -10\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -4.5\text{V}, R_{\text{GS}} = 6\Omega$		10		
Rise Time ^{1,2}	t_r			20		nS
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			15		
Fall Time ^{1,2}	t_f			12		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				-2	
Pulsed Current ³	I_{SM}				-8	A
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{\text{GS}} = 0\text{V}$			1.2	V

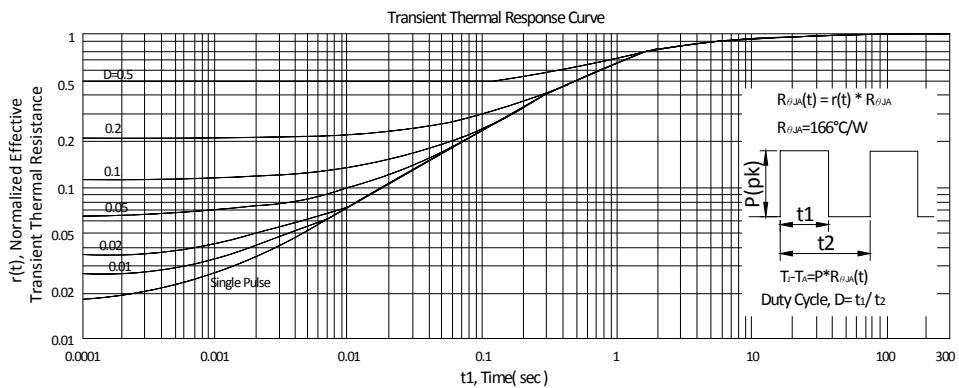
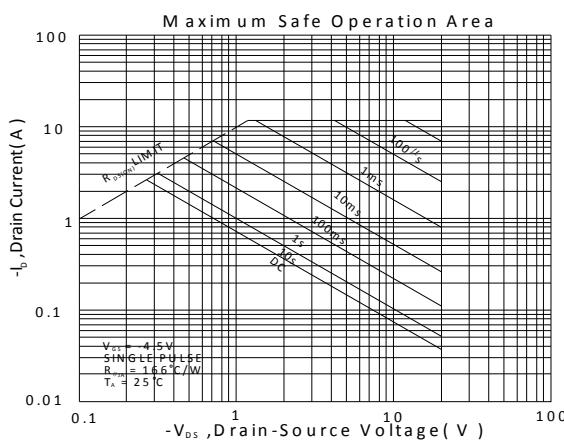
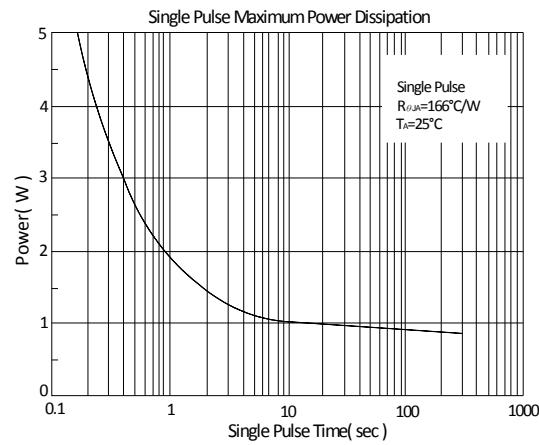
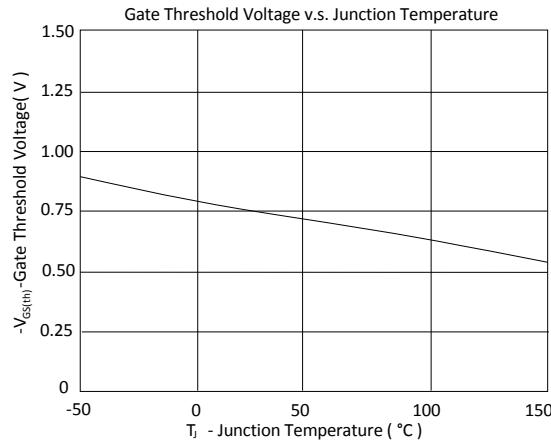
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

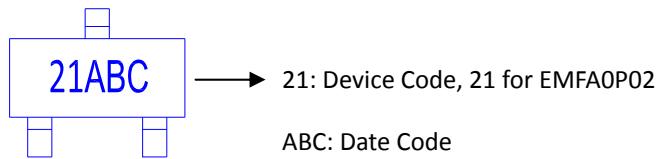
TYPICAL CHARACTERISTICS



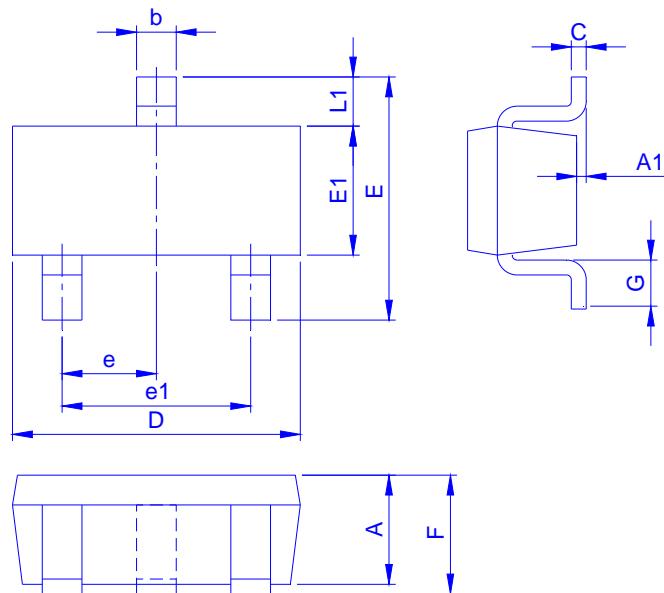


Ordering & Marking Information:

Device Name: EMFA0P02JS for SOT-23



Outline Drawing



Dimension in mm

Dimension	A	A1	b	C	D	E	E1	e	e1	F	G	L1
Min.	0.70	0	0.3	0.08	2.80	2.25	1.2	0.90		0.80	0.3	0.50
Typ.					2.90			0.95	1.9			
Max.	1.15	0.1	0.5	0.20	3.02	3.00	1.7	1.00		1.25	0.6	0.75

Footprint

